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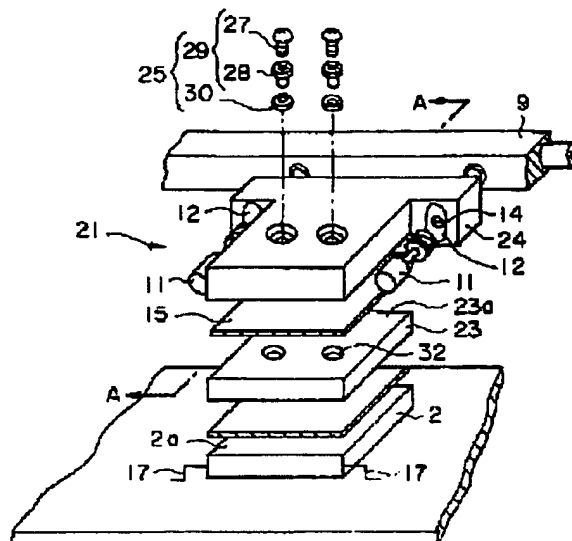
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TITLE : MOUNTING STRUCTURE FOR IC  
COOLING MECHANISM



**ABSTRACT :** PROBLEM TO BE SOLVED: To prevent the peeling of an IC from a printed board by constituting a mounting structure of a first heat radiating plate with which the IC comes into contact, a second heat radiating plate directly fixed to a cooling mechanism, and a pressing mechanism which brings the first and second heat radiating plates with each other with a fixed pressing force.

**SOLUTION:** A mounting structure 21 is constituted of a lower heat radiating plate 23 which is arranged so that the plate 23 may come into contact with the upper surface 2a of an IC 2, an upper heat radiating plate 24 which is arranged so that the plate 24 may come into contact with the upper surface 23a of the plate 23 and a cooling pipe 9, and a pressing mechanism 25 which brings the plates 23 and 24 into contact with each other with a fixed pressing force. The lower heat radiating plate 23 is stuck to the upper surface 2a of an IC 2 mounted with a printed board with a heat conductive adhesive 15. When the heat radiating plates 24 and 23 are fixed with screws 27 from the upper surface side of the plate 23, sleeves 28 and wave washers 30 are attached. Therefore, the durability of an IC cooling mechanism can be improved by preventing the peeling of the IC 2 from the printed board.

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